524288-word × 8-bit High Speed CMOS Static RAM

HITACHI

ADE-203-762(Z) Preliminary Rev. 0.0 Mar. 27, 1997

Description

The HM628511H Series is an asyncronous high speed static RAM organized as 512-k word \times 8-bit. It has realized high speed access time by employing CMOS process and high speed circuit designing technology. It is most appropriate for the application which requires high speed, high density memory and wide bit width configuration, such as cache and buffer memory in system. It is packaged in 400-mil 36-pin plastic SOJ.

Features

- Single 5.0 V supply : $5.0 V \pm 10 \%$
- Access time 10 ns/12 ns/15 ns (max)
- Completely static memory
 No clock or timing strobe required
- Equal access and cycle times
- Directly TTL compatible
 - All inputs and outputs
- Center V_{CC} and V_{SS} type pinout

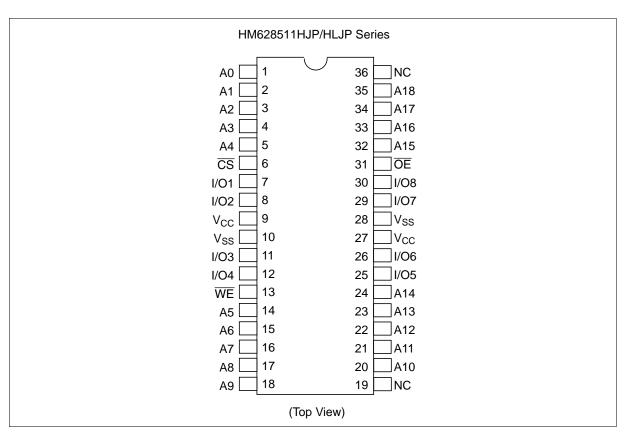
Ordering Information

| Туре No. | Access time | Package |
|-----------------|-------------|-------------------------------------|
| HM628511HJP-10 | 10 ns | 400-mil 36-pin plastic SOJ (CP-36D) |
| HM628511HJP-12 | 12 ns | |
| HM628511HJP-15 | 15 ns | |
| HM628511HLJP-10 | 10 ns | |
| HM628511HLJP-12 | 12 ns | |
| HM628511HLJP-15 | 15 ns | |

Preliminary: The specifications of this device are subject to change without notice. Please contact to your nearest Hitachi's sales Dept. regarding specifications.



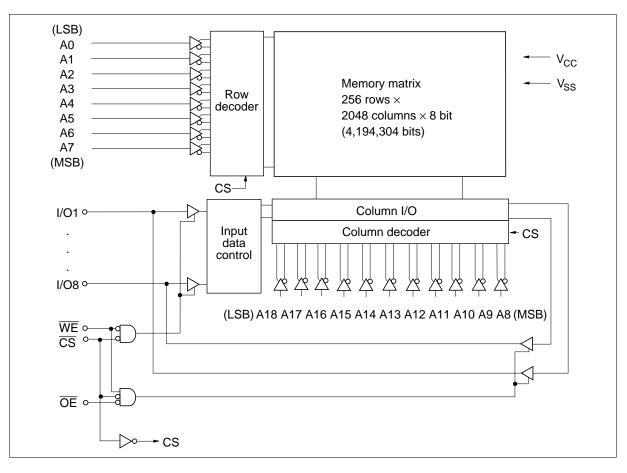
Pin Arrangement



Pin Description

| Pin name | Function |
|-----------------|-------------------|
| A0 to A18 | Address input |
| I/O1 to I/O8 | Data input/output |
| CS | Chip select |
| ŌĒ | Output enable |
| WE | Write enable |
| V _{cc} | Power supply |
| V _{ss} | Ground |
| NC | No connection |

Block Diagram



Function Table

| CS | ŌE | WE | Mode | V _{cc} current | I/O | Ref. cycle |
|----|----|----|----------------|---------------------------|--------|-----------------------|
| Н | × | × | Standby | $I_{\rm SB}, I_{\rm SB1}$ | High-Z | _ |
| L | Н | Н | Output disable | I _{cc} | High-Z | — |
| L | L | Н | Read | I _{cc} | Dout | Read cycle (1) to (3) |
| L | Н | L | Write | I _{cc} | Din | Write cycle (1) |
| L | L | L | Write | I _{cc} | Din | Write cycle (2) |
| | | | | | | |

Note: ×: H or L

Absolute Maximum Ratings

| Parameter | Symbol | Value | Unit |
|---|-----------------|--------------------------------------|------|
| Supply voltage relative to V_{ss} | V _{cc} | –0.5 to +7.0 | V |
| Voltage on any pin relative to V_{ss} | V _T | -0.5^{*1} to V _{cc} +0.5 | V |
| Power dissipation | P _T | 1.0 ^{*2} /1.5 ^{*3} | W |
| Operating temperature | Topr | 0 to +70 | °C |
| Storage temperature | Tstg | -55 to +125 | °C |
| Storage temperature under bias | Tbias | -10 to +85 | °C |

Notes: 1. V_{T} min = -2.5 V for pulse width (under shoot) \leq 10 ns

2. At still air condition

3. At air flow \geq 1.0 m/s

Recommended DC Operating Conditions (Ta = 0 to $+70^{\circ}$ C)

| Parameter | Symbol | Min | Тур | Мах | Unit |
|----------------|--------------------------------|--------|-----|-----------------------|------|
| Supply voltage | V _{cc} *2 | 4.5 | 5.0 | 5.5 | V |
| | V _{SS} * ³ | 0 | 0 | 0 | V |
| Input voltage | V _{IH} | 2.2 | — | V _{cc} + 0.5 | V |
| | V _{IL} | -0.5*1 | — | 0.8 | V |

Notes: 1. V_{IL} min = -2.0 V for pulse width (under shoot) \leq 10 ns

2. The supply voltage with all V_{cc} pins must be on the same level.

3. The supply voltage with all $\rm V_{\rm ss}$ pins must be on the same level.

| Parameter | | Symbol | Min | Typ*¹ | Max | Unit | Test conditions |
|--------------------------------|-------------|--------------------|-----|-------|-------------------|------|---|
| Input leakage current | | ll _u l | _ | _ | 2 | μA | Vin = V_{ss} to V_{cc} |
| Output leakage current | | II _{lo} I | — | _ | 2 | μA | Vin = V_{ss} to V_{cc} |
| Operation power supply current | 10 ns cycle | I _{cc} | — | — | 240 | mA | $\overline{CS} = V_{IL}$, lout = 0 mA Other inputs = $V_{IH}V_{IL}$ |
| | 12 ns cycle | I _{cc} | _ | _ | 200 | | |
| | 15 ns cycle | I _{cc} | — | _ | 190 | | |
| Standby power supply current | 10 ns cycle | I _{SB} | _ | — | 100 | mA | $\overline{CS} = V_{IH},$ Other inputs = V_{IH}/V_{IL} |
| | 12 ns cycle | I _{SB} | — | _ | 100 | | |
| | 15 ns cycle | I _{SB} | — | _ | 100 | | |
| | | I _{SB1} | _ | _ | 10 | mA | $\begin{array}{l} V_{\text{CC}} \geq \overline{\text{CS}} \geq V_{\text{CC}} \text{ - } 0.2 \text{ V}, \\ \textbf{(1)} \ 0 \ V \leq Vin \leq 0.2 \text{ V or} \\ \textbf{(2)} \ V_{\text{CC}} \geq Vin \geq V_{\text{CC}} \text{ - } 0.2 \text{ V} \end{array}$ |
| | | | *2 | *2 | 1.0* ² | _ | |
| Output voltage | | V _{ol} | _ | — | 0.4 | V | $I_{OL} = 8 \text{ mA}$ |
| | | V _{OH} | 2.4 | _ | — | V | $I_{OH} = -4 \text{ mA}$ |

DC Characteristics (Ta = 0 to +70°C, $V_{CC} = 5.0 \text{ V} \pm 10 \%$, $V_{SS} = 0 \text{V}$)

Notes: 1. Typical values are at V_{cc} = 5.0 V, Ta = +25°C and not guaranteed.

2. This characteristics is guaranteed only for L-version.

Capacitance (Ta = 25° C, f = 1.0 MHz)

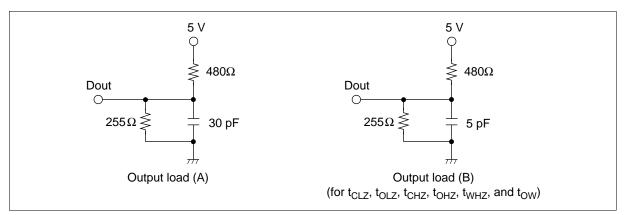
| Parameter | Symbol | Min | Тур | Max | Unit | Test conditions |
|----------------------------|--------|-----|-----|-----|------|-----------------|
| Input capacitance*1 | Cin | _ | _ | 6 | pF | Vin = 0 V |
| Input/output capacitance*1 | CI/O | — | — | 8 | pF | $V_{I/O} = 0 V$ |

Note: 1. This parameter is sampled and not 100% tested.

AC Characteristics (Ta = 0 to +70°C, V_{CC} = 5.0 V ± 10 %, unless otherwise noted.)

Test Conditions

- Input pulse levels: 3.0 V/0.0 V
- Input rise and fall time: 3 ns
- Input and output timing reference levels: 1.5V
- Output load: See figures (Including scope and jig)



Read Cycle

| | | HM628511H | | | | | | | |
|------------------------------------|------------------|-----------|---------|-----|---------|-----|-----|------|-------|
| | | -10 | | -12 | | -15 | | _ | |
| Parameter | Symbol | Min | Min Max | | Min Max | | Max | Unit | Notes |
| Read cycle time | t _{RC} | 10 | | 12 | | 15 | | ns | |
| Address access time | t _{AA} | _ | 10 | — | 12 | | 15 | ns | |
| Chip select access time | t _{ACS} | — | 10 | — | 12 | | 15 | ns | |
| Output enable to outpput valid | t _{oe} | _ | 5 | — | 6 | | 8 | ns | |
| Output hold from address change | t _{он} | 3 | | 3 | | 3 | | ns | |
| Chip select to output in low-Z | t _{cLZ} | 3 | _ | 3 | _ | 3 | _ | ns | 1 |
| Output enable to output in low-Z | t _{oLZ} | 0 | | 0 | | 0 | | ns | 1 |
| Chip deselect to output in high-Z | t _{cHZ} | | 5 | — | 6 | | 8 | ns | 1 |
| Output disable to output in high-Z | t _{oHZ} | | 5 | | 6 | | 8 | ns | 1 |

Write Cycle

| | | HM628511H | | | | | | | |
|------------------------------------|------------------|-----------|-----|-----|-----|-----|-----|------|-------|
| | | -10 | | -12 | | -15 | | - | |
| Parameter | Symbol | Min | Max | Min | Max | Min | Max | Unit | Notes |
| Write cycle time | t _{wc} | 10 | | 12 | _ | 15 | | ns | |
| Address valid to end of write | t _{AW} | 6 | _ | 8 | _ | 10 | _ | ns | |
| Chip select to end of write | t _{cw} | 6 | _ | 8 | _ | 10 | _ | ns | 9 |
| Write pulse width | t _{wP} | 6 | _ | 8 | _ | 10 | _ | ns | 8 |
| Address setup time | t _{AS} | 0 | _ | 0 | _ | 0 | | ns | 6 |
| Write recovery time | t _{wR} | 0 | _ | 0 | _ | 0 | | ns | 7 |
| Data to write time overlap | t _{DW} | 5 | _ | 6 | _ | 8 | | ns | |
| Data hold from write time | t _{DH} | 0 | _ | 0 | _ | 0 | | ns | |
| Write disable to output in low-Z | t _{ow} | 3 | _ | 3 | _ | 3 | | ns | 1 |
| Output disable to output in high-Z | t _{oHZ} | — | 5 | _ | 6 | _ | 8 | ns | 1 |
| Write enable to output in high-Z | t _{wHZ} | | 5 | — | 6 | — | 8 | ns | 1 |
| | | | | | | | | | |

Note: 1. Transition is measured ±200 mV from steady voltage with Load (B). This parameter is sampled and not 100% tested.

2. Address should be valid prior to or coincident with \overline{CS} transition low.

3. $\overline{\text{WE}}$ and/or $\overline{\text{CS}}$ must be high during address transition time.

 if CS and OE are low during this period, I/O pins are in the output state. Then, the data input signals of opposite phase to the outputs must not be applied to them.

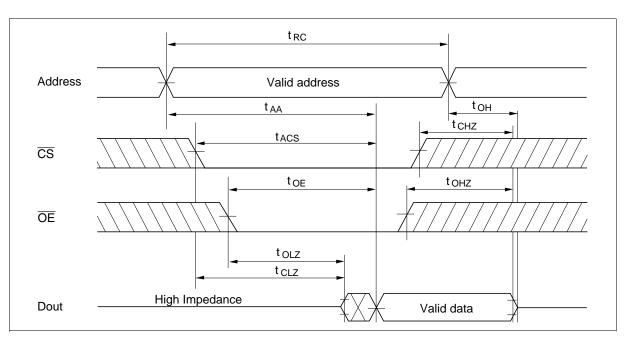
5. If the CS low transition occurs simultaneously with the WE low transition or after the WE transition, output remains a high impedance state.

6. t_{AS} is measured from the latest address transition to the later of \overline{CS} or \overline{WE} going low.

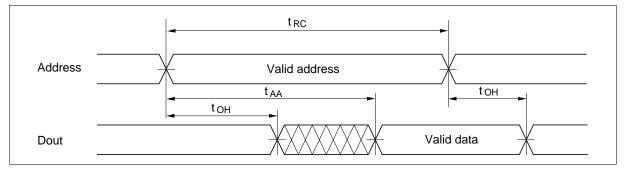
- 7. t_{WR} is measured from the earlier of \overline{CS} or \overline{WE} going high to the first address transition.
- 8. A write occurs during the overlap of a low CS and a low WE. A write begins at the latest transition among CS going low and WE going low. A write ends at the earliest transition among CS going high and WE going high. t_{wP} is measured from the beginning of write to the end of write.
- 9. t_{cw} is measured from the later of \overline{CS} going low to the the end of write.

Timing Waveforms

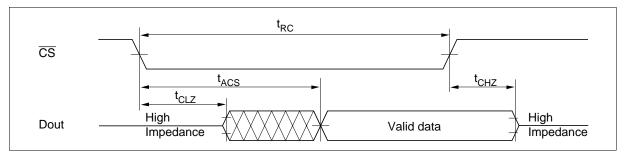
Read Timing Waveform (1) ($\overline{WE} = V_{IH}$)



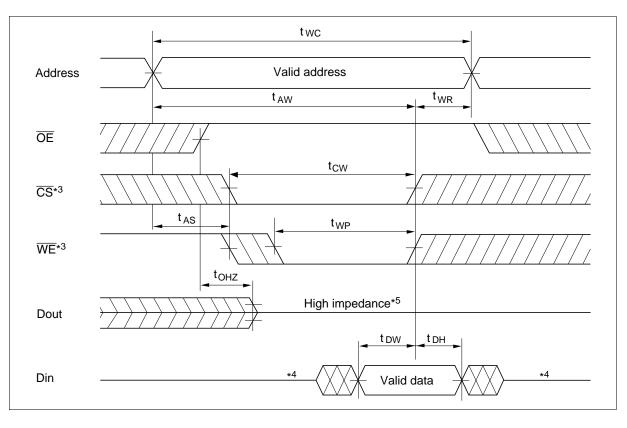
Read Timing Waveform (2) ($\overline{WE} = V_{IH}, \overline{CS} = V_{IL}, \overline{OE} = V_{IL}$)

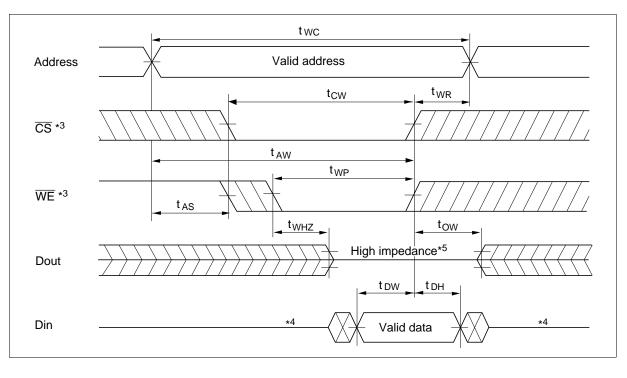


Read Timing Waveform (3) $(\overline{WE} = V_{II}, \overline{CS} = V_{IL}, \overline{OE} = V_{IL})^{*2}$



Write Timing Waveform (1) (WE Controlled)





Write Timing Waveform (2) ($\overline{\text{CS}}$ Controlled)

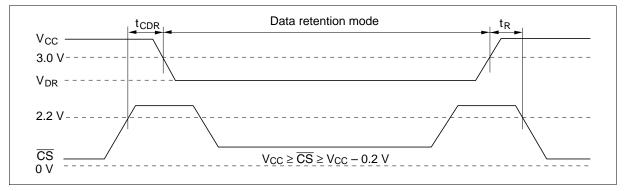
Low V_{CC} Data Retention Characteristics (Ta = 0 to 70°C)

This characteristics is guaranteed only for L-version.

| Parameter | Symbol | Min | Typ*1 | Max | Unit | Test conditions |
|--------------------------------------|-------------------|-----|-------|-----|------|--|
| V_{cc} for data retention | V_{DR} | 2.0 | _ | _ | V | $\begin{array}{l} V_{\mathrm{CC}} \geq \overline{\mathrm{CS}} \geq V_{\mathrm{CC}} - 0.2 \ V \\ (1) 0 \ V \leq Vin \leq 0.2 \ V \ or \\ (2) V_{\mathrm{CC}} \geq Vin \geq V_{\mathrm{CC}} - 0.2 \ V \end{array}$ |
| Data retention current | I _{CCDR} | — | 2 | 300 | μA | $\begin{array}{l} V_{cc} = 3 \ V, \ V_{cc} \geq \overline{CS} \geq V_{cc} - 0.2 \ V \\ (1) \ 0 \ V \leq Vin \leq 0.2 \ V \ or \\ (2) \ V_{cc} \geq Vin \geq V_{cc} - 0.2 \ V \end{array}$ |
| Chip deselect to data retention time | t _{cdr} | 0 | — | _ | ns | See retention waveform |
| Operation recovery time | t _R | 5 | | | ms | _ |

Note: 1. Typical values are at $V_{cc} = 3.0 \text{ V}$, Ta = 25°C, and not guaranteed.

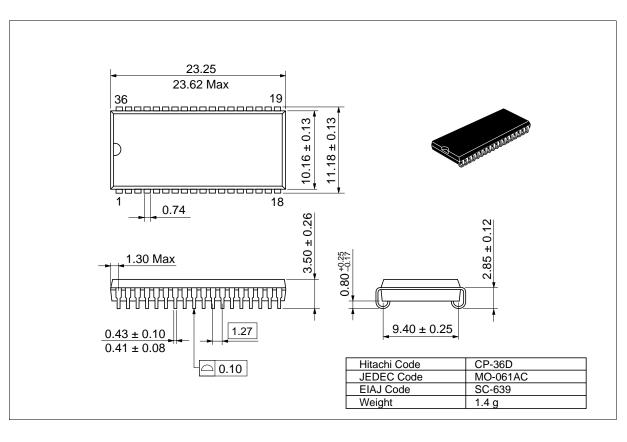
Low V_{CC} Data Retention Timing Waveform



Package Dimensions

HM628511HJP/HLJP Series (CP-36D)

Unit: mm



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Revision Record

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